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(54) CIRCUIT BOARD, SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING CIRCUIT BOARD

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(57)ABSTRACT

A circuit board includes an interconnect and an insulating layer that covers the interconnect. The interconnect includes a first interconnect that is formed to serve as a recognition mark of which planar shape is a predetermined shape. The insulating layer has a through-hole of which planar shape is variant and that penetrates the insulating layer in a thickness direction of the insulating layer such that an entire upper surface of the first interconnect is exposed. The through-hole includes a first through-hole of which planar shape is a predetermined shape and that penetrates the insulating layer in the thickness direction such that the entire upper surface of the first interconnect is exposed and a second throughhole that serves as part of an inner wall surface of the first through-hole and that penetrates the insulating layer in the thickness direction.

